**Application Guideline for Interconnecting Devices with Large Ground Pads Such as QFN**

*This guideline applies to single PariPoser contact and does not apply to contactors incorporating PariProbe or flex structure.*

Optimum interconnection between a device with large ground pads and a PCB is achieved with segmentation of the matching ground pad on the PCB. Shown below are two examples of how this is done. The example on the left shows an array of surface pads with the same general size and pitch as the device contacts. The example on the right shows a lattice structure which can provide the same effect but perhaps assures better electrical uniformity.

The general rules for designing the PCB are:

- Each ground pad should have same general area as surrounding contact pads.
- Maximize open area between pads with goal of ~2/3 of total area being open space. This provides adequate volume for incompressible silicone to flow into.
- Gap between ground pads and contact pads must meet PariPoser minimum design rule of 40% of pitch.
- Ground pad height should be same as contact pad height.